



HK B 0.11 T U

Bgrbc Knbs c

Dc rspc

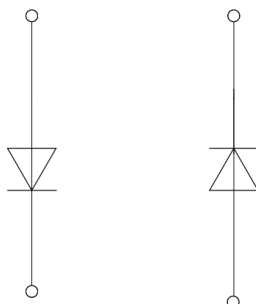
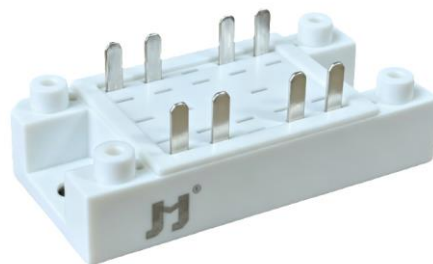
- A package of series of two diodes
- Heat transfer through alumina ceramic and metal substrate
- Welding by vacuum welding technology, which provide high reliability

prbsar sk k p

p k crcp	T sc	Sl g
V_{RRM}	1600	V
$I_{F(AV)} (@ T_C = 100^{\circ}C)$	120	A
$I_{FSM} (@ t_p = 10ms)$	3360	A
$V_F(Max)$	1.60	V

nn g rgrl

- AC converter
- Inverter
- DC motor



msrc K vsk P rge (@ $T_C = 25^{\circ}C$ unless otherwise specified)

p k crcp	Anl bggrl	k m	T sc	Sl g
Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}C$	V_{RRM}	1600	V
Non-repetitive peak reverse voltage	$T_{vj} = 25^{\circ}C$	V_{RSM}	1700	V
Average forward current	$T_C = 100^{\circ}C$	$I_{F(AV)}$	120	A
Forward surge current	1/2 cycle, Sine wave, 50Hz $T_{vj} = 25^{\circ}C$	I_{FSM}	3360	A
I^2t value for fusing		I^2t	56400	A^2s
RMS isolation voltage	A.C 50Hz(1s/1min)	V_{ISO}	3600/3000	V
Junction temperature range		T_J	-40 ~ +150	
Storage temperature range		T_{stg}	-40 ~ +125	

**Characteristics of the diode** (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Unit	Test Condition			Value
			I_F	V_R	V_{TO}	
Peak forward voltage	V_F		$I_F=360\text{A}$, $t_p=380\mu\text{s}$			1.60 V
Reverse leakage current	I_{RRM}		$V_R = V_{RRM}$, $T_{vj} = 25^\circ\text{C}$			100 μA
			$V_R = V_{RRM}$, $T_{vj} = 150^\circ\text{C}$			40 mA
Threshold voltage	V_{TO}		$T_{vj} = 150^\circ\text{C}$, for power loss calculation only			0.85 V
Dynamic resistance	r_T					1.5 $\text{m}\Omega$

Thermal Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Unit	Test Condition			Value
			$R_{th(j-c)}$	$R_{th(c-s)}$	M	
Thermal resistance, junction to case	$R_{th(j-c)}$		per diode			0.29 /W
Thermal resistance, case to heatsink	$R_{th(c-s)}$		per diode			0.12 /W
Mounting torque	M		Module and heatsink fixed torque M5			1.7 N m

Package and Pinning

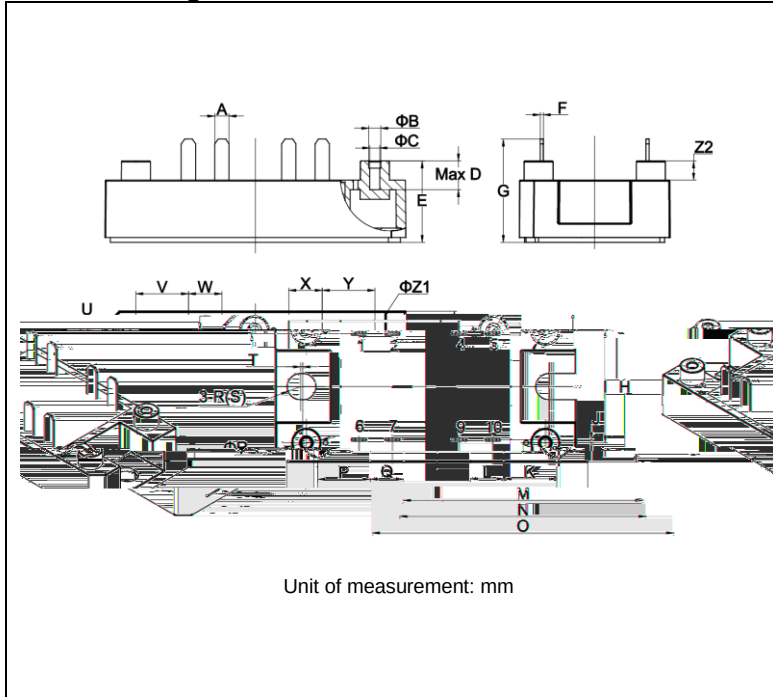
Part Number	Package	Pin	Weight	Quantity	Quantity
JMD120K316V1W	JMD120K316V1W	V1	43g/PCS	60 PCS	360 PCS



HK B 0. I



ai ec Msr g c & k



Ref	Dimensions					
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	2.85	3	3.15	0.112	0.118	0.124
B	2.3	2.5	2.7	0.091	0.098	0.106
C	1.9	2.1	2.3	0.075	0.083	0.091
D			6			0.236
E	16.25	17	17.75	0.640	0.669	0.699
F	0.55	0.65	0.75	0.022	0.026	0.030
G	20.85	21.6	22.35	0.821	0.850	0.880
H	30.85	31.6	32.35	1.215	1.244	1.274
I	23	23.5	24	0.906	0.925	0.945
J	0.17	0.67	1.17	0.007	0.026	0.046
K	10.5	11	11.5	0.413	0.433	0.453
L	6.5	7	7.5	0.256	0.276	0.295
M	49.5	50	50.5	1.949	1.969	1.988
N	51	51.5	52	2.008	2.028	2.047
O	62.25	63	63.75	2.451	2.480	2.510
P	10.5	11	11.5	0.413	0.433	0.453
Q	6.5	7	7.5	0.256	0.276	0.295
R	5.6	6.1	6.6	0.220	0.240	0.260
S	0.025	0.026	0.027	0.001	0.001	0.001
T	0.020	0.026	0.03	0.001	0.001	0.001
U	0.025	0.043	0.07	0.001	0.001	0.001
V	0.413	0.433	0.453	0.017	0.017	0.017
W	7.5	0.256	0.276	0.295	0.01	0.01
X	7.5	0.256	0.276	0.295	0.01	0.01
Y	11.5	0.413	0.433	0.453	0.01	0.01
Z1	6.6	0.220	0.240	0.260	0.01	0.01
Z2	4.5	0.136	0.157	0.177	0.01	0.01



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